

PRODUCT SPECIFICATION SHEET

Product Name: Signamax® High Density Modular UTP Patch Panels

Property	Value
Transmission Media	Unscreened UTP
Jack Type	8 position, 8 contact
Wiring Scheme	T568A & T568B
Wire Gauge	24-22 AWG
Insulation resistance	500 MOhm @ 100 VDC
Dielectric Withstanding Voltage	1,000 Vdc/ac peak contact-to-contact @ 60 Hz for 1 min
Spring wire contact resistance	max 20 mOhm
IDC contact resistance	max 2.5 mOhm
Physical	
Panel Housing Material	1.6 mm (0.063 in) Carbon Steel
Connector Housing Material	Flame Retardant Thermoplastic
Conductor Material	Phosphor Bronze Alloy plated with 50 µin of Gold over 70-100 µin of Nickel
Dimensions	1U: 19"W x 1.75" H x 1.25" D (48.26 x 4.44 x 3.17 cm)
	2U: 19"W x 3.5" H x 1.25" D (48.26 x 8.89 x 3.17 cm)
Weight	1U: 1.75 lbs (0.79 kg)
	2U: 3.1 lbs (1.41 kg)
Mechanical	
Retention Force	50 N (11 lbf) for 60 ± 5 s
Mating Cycle Life	min 750 cycles
Storage Temperature	-40 °C - 70 °C (-40 °F - 158 °F)
Operating Temperature	-10 °C - 60 °C (14 °F - 140 °F)
Relative Humidity (Operating)	95%
Applications	X.21, V.11, S0, ISDN, CSMA/CD 10BASE-T, 100BASE-TX, 100BASE-T4, 100BASE-T2, 1000BASE-T, 10GBASE-T (up to 180'/55 m), TR 4/16/100, 100BASE-VG, ATM LAN 25/51/155, TP-PMD
Industry Standards	ANSI/TIA-568-C.2 SAE 1010 UL 94V-0 IEC 60603-7 FCC Part 68 Subpart F RoHS